

STV9302B

Vertical Deflection Booster for 2-A_{PP} TV (50-60 Hz) Applications with 70-V Flyback Generator

DATASHEET

1/15

Main Features

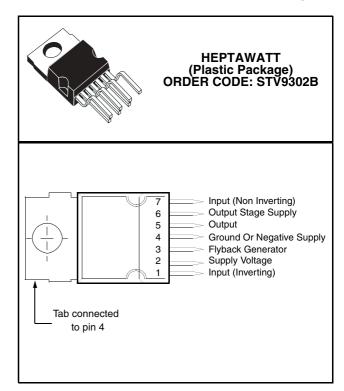
- Power Amplifier
- Flyback Generator
- Output Current up to 2 App
- Thermal Protection

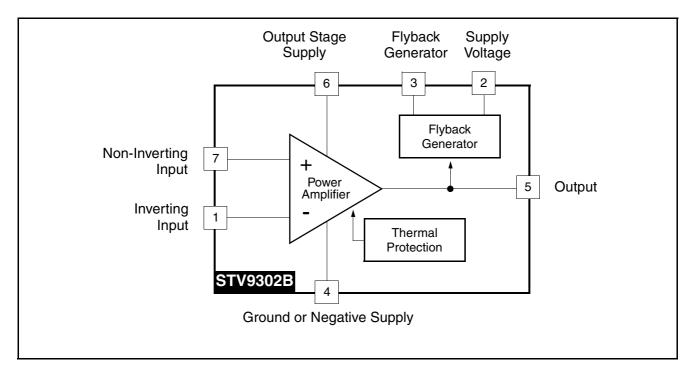
Description

The STV9302B is a vertical deflection booster designed for TV (50-60 Hz) applications.

This device, supplied with up to 35 V, provides up to 2 App output current to drive the vertical deflection yoke.

The internal flyback generator delivers flyback voltages up to 70 V.





February 2005 Revision 0.1 ADCS No. 7811475 STMicroelectronics Confidential

1 Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
Voltage			
V _S	Supply Voltage (pin 2) - Note 1 and Note 2	40	٧
V ₅ , V ₆	Flyback Peak Voltage - Note 2	70	٧
V ₃	Voltage at Pin 3 - Note 2, Note 3 and Note 6	-0.4 to (V _S + 3)	٧
V ₁ , V ₇	Amplifier Input Voltage - Note 2, Note 6 and Note 7	- 0.4 to (V _S + 2) or +40	V
Current		,	
I ₀ (1)	Output Peak Current at f = 50 to 65 Hz, t ≤10 µs - Note 4	±5	Α
I ₀ (2)	Output Peak Current non-repetitive - Note 5	±2	Α
I _{3 Sink}	Sink Current, t < 1 ms - Note 3	1.5	Α
I _{3 Source}	Source Current, t < 1 ms	1.5	Α
I ₃	Flyback pulse current at f = 50 to 65 Hz, t ≤10 µs - Note 4	±5	Α
ESD Susceptibili	ty		
ESD1	Human body model (100 pF discharged through 1.5 k Ω)	2	kV
ESD2	EIAJ Standard (200 pF discharged through 0 Ω)	300	٧
Temperature	·	· .	
T _s	Storage Temperature	-40 to 150	°C
Tj	Junction Temperature	+150	°C

- Note:1. Usually the flyback voltage is slightly more than $2 \times V_S$. This must be taken into consideration when setting $V_{S.}$
 - 2. Versus pin 4
 - 3. V3 is higher than V_S during the first half of the flyback pulse.
 - 4. Such repetitive output peak currents are usually observed just before and after the flyback pulse.
 - 5. This non-repetitive output peak current can be observed, for example, during the Switch-On/Switch-Off phases. This peak current is acceptable providing the SOA is respected (Figure 8 and Figure 9).
 - 6. All pins have a reverse diode towards pin 4, these diodes should never be forward-biased.
 - 7. Input voltages must not exceed the lower value of either V_S + 2 or 40 volts.

2 Thermal Data

Symbol	Parameter	Value	Unit
R_{thJC}	Junction-to-Case Thermal Resistance	3	°C/W
T _T	Temperature for Thermal Shutdown	150	°C
T _J	Recommended Max. Junction Temperature	120	°C

3 Electrical Characteristics

 $(V_S = 32 \text{ V}, T_{AMB} = 25^{\circ}\text{C}, \text{ unless otherwise specified})$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
Supply			· ·	•	•	•	
Vs	Operating Supply Voltage Range (V ₂ -V ₄)	Note 8	10		35	V	
l ₂	Pin 2 Quiescent Current	$I_3 = 0, I_5 = 0$		5	20	mA	1
I ₆	Pin 6 Quiescent Current	$I_3 = 0$, $I_5 = 0$, $V_6 = 35v$	$I_3 = 0, I_5 = 0, V_6 = 35v$ 8		50	mA	1
Input			I		•	•	
I ₁	Input Bias Current	V ₁ = 1 V, V ₇ = 2.2 V		- 0.6	-1.5	μA	1
I ₇	Input Bias Current	V ₁ = 2.2 V, V ₇ = 1 V		- 0.6	-1.5	μA	
V _{IR}	Operating Input Voltage Range		0		V _S - 2	V	
V _{IO}	Offset Voltage			2		mV	
ΔV _{I0} /dt	Offset Drift versus Temperature			10		μV/°C	
Output			L			ı	
I ₀	Operating Peak Output Current	f = 50 to 60 Hz			±1	Α	
V _{5L}	Output Saturation Voltage to pin 4	I ₅ = 1 A		1	1.7	V	3
V _{5H}	Output Saturation Voltage to pin 6	I ₅ = -1 A		1.8	2.3	V	2
Miscellan	eous		· I			ı	
G	Voltage Gain		80			dB	
V _{D5-6}	Diode Forward Voltage Between pins 5-6	I ₅ = 1 A		1.4	2	V	
V _{D3-2}	Diode Forward Voltage between pins 3-2	I ₃ = 1 A		1.3	2	٧	
V_{3SL}	Saturation Voltage on pin 3	I ₃ = 20 mA		0.4	1	V	3
V _{3SH}	Saturation Voltage to pin 2 (2nd part of flyback)	I ₃ = -1 A		2.1		V	

^{8.} In normal applications, the peak flyback voltage is slightly greater than 2 x (V_S - V_4). Therefore, (V_S - V_4) = 35 V is not allowed without special circuitry.

Figure 1: Measurement of I_1 , I_2 and I_6

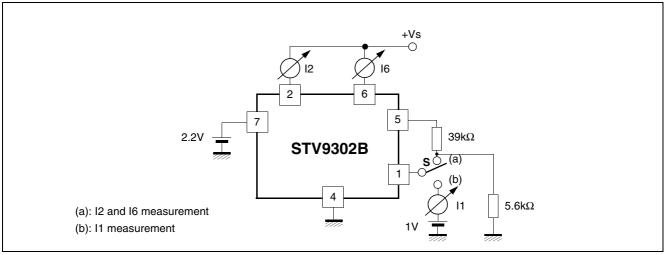


Figure 2: Measurement of V_{5H}

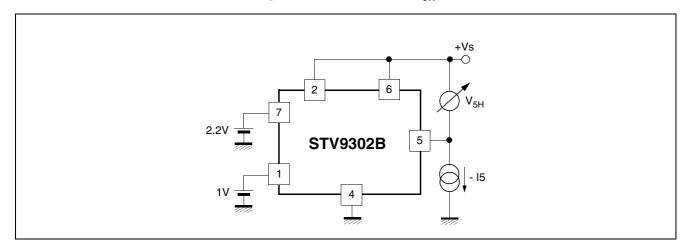
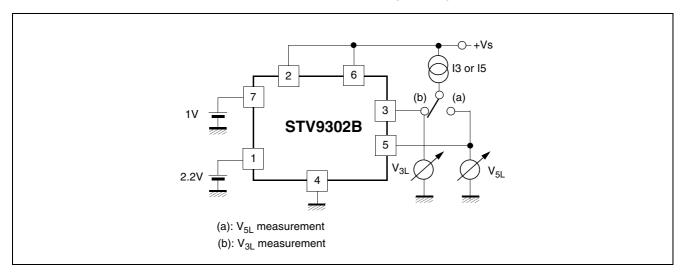


Figure 3: Measurement of V_{3L} and V_{5L}



STV9302B Application Hints

4 Application Hints

The yoke can be coupled either in AC or DC.

4.1 DC-coupled Application

When DC coupled (see Figure 4), the display vertical position can be adjusted with input bias. On the other hand, 2 supply sources (V_S and $-V_{EE}$) are required.

O+Vs Output C_F (47 to 100µF) Voltage Output Flyback Current Generator Vref Power **Amplifier** Vertical Position Adjustment 5 1 Thermal Yoke R3 1.5Ω Rd(*) Safety V_{M} 0.22µF $V_{\underline{m}}$ $-V_{\mathsf{EE}}$ 0.1µF R2 R1 $\frac{Ly}{50\mu s}$ < Rd < $\frac{Ly}{20\mu s}$ (*) recommended:

Figure 4: DC-coupled Application

4.1.1 Application Hints

For calculations, treat the IC as an op-amp, where the feedback loop maintains $V_1 = V_7$.

4.1.1.1 Centering

Display will be centered (null mean current in yoke) when voltage on pin 7 is (R₁ is negligible):

$$V_7 = \frac{V_M + V_m}{2} \times \left(\frac{R_2}{R_2 + R_3}\right)$$

Application Hints STV9302B

4.1.1.2 Peak Current

$$I_{P} = \frac{(V_{M} - V_{m})}{2} \times \frac{R_{2}}{R_{1} \times R_{3}}$$

Example: for $V_m = 2 V$, $V_M = 5 V$ and $I_P = 1 A$

Choose R_1 in the 1 Ω range, for instance $R_1=1$ Ω

From equation of peak current: $\frac{R_2}{R_3} = \frac{2 \times I_P \times R_1}{V_M - V_m} = \frac{2}{3}$

Then choose R_2 or R_3 . For instance, if R_2 = 10 k Ω , then R_3 = 15 k Ω

Finally, the bias voltage on pin 7 should be:

$$V_7 = \frac{V_M + V_m}{2} \times \frac{1}{1 + \frac{R_3}{R_2}} = \frac{7}{2} \times \frac{1}{2.5} = 1.4V$$

4.1.2 Ripple Rejection

When both ramp signal and bias are provided by the same driver IC, you can gain natural rejection of any ripple caused by a voltage drop in the ground (see Figure 5), if you manage to apply the same fraction of ripple voltage to both booster inputs. For that purpose, arrange an intermediate point in the bias resistor bridge, such that $(R_8 / R_7) = (R_3 / R_2)$, and connect the bias filtering capacitor between the intermediate point and the local driver ground. Of course, R_7 should be connected to the booster reference point, which is the ground side of R_1 .

Flyback Generator Reference Power Amplifier Voltage R_9 5 R_7 Thermal Rd Yoke Ly 4 Ramp Signal R_3 R_2 R_1 Driver Source of Ripple Ground

Figure 5: Ripple Rejection

Application Hints STV9302B

4.2 **AC-Coupled Applications**

In AC-coupled applications (See Figure 6), only one supply (V_S) is needed. The vertical position of the scanning cannot be adjusted with input bias (for that purpose, usually some current is injected or sunk with a resistor in the low side of the yoke).

O +Vs Output \downarrow C_F (47 to 100 μ F) Voltage Output Flyback Current Generator Power Amplifier 5 Thermal Yoke 1.5Ω Rd(*) Safety V_{M} V_{m} R_2 $\frac{Ly}{50us}$ < Rd < $\frac{Ly}{20us}$ (*) recommended: R_1

Figure 6: AC-coupled Application

Application Hints 4.2.1

Gain is defined as in the previous case:

$$I_{p} = \frac{V_{M} - V_{m}}{2} \times \frac{R_{2}}{R_{1} \times R_{2}}$$

Choose R₁ then either R₂ or R₃. For good output centering, V₇ must fulfill the following equation:
$$\frac{\frac{V_S}{2} - V_7}{R_4 + R_5} = \frac{V_7 - \frac{V_M + V_m}{2}}{R_3} + \frac{V_7}{R_2}$$

or

$$v_7 \times \left(\frac{1}{R_3} + \frac{1}{R_2} + \frac{1}{R_4 + R_5}\right) = \left(\frac{v_s}{2(R_4 + R_5)} + \frac{v_m + v_m}{2 \times R_3}\right)$$

Application Hints STV9302B

 C_S performs an integration of the parabolic signal on C_L , therefore the amount of S correction is set by the combination of C_L and C_s .

4.3 Application with Differential-output Drivers

Certain driver ICs provide the ramp signal in differential form, as two current sources i₊ and i_with opposite variations.

○+Vs Output Voltage C_F (47 to 100 μF) 0.1µF 2 Output Differential Output Driver IC Flyback Current Generator Power **Amplifier** √-i_p 5 R_7 Thermal Yoke 1.5Ω Rd(*) Safety Ly $-V_{\mathsf{EE}}$ 470uF R_2 R_1 $\frac{Ly}{50\mu s} < Rd < \frac{Ly}{20\mu s}$ (*) Recommended:

Figure 7: Using a Differential-output Driver

Let us set some definitions:

- i_{cm} is the common-mode current: $i_{cm} = \frac{1}{2}(i_+ + i_-)$
- at peak of signal, $i_+ = i_{cm} + i_p$ and $i_- = i_{cm} i_p$, therefore the peak differential signal is i_p (- i_p) = 2 i_p , and the peak-peak differential signal, $4i_p$.

The application is described in Figure 7 with DC yoke coupling. The calculations still rely on the fact that V_1 remains equal to V_7 .

STV9302B Application Hints

4.3.1 Centering

When idle, both driver outputs provide i_{cm} and the yoke current should be null (R₁ is negligible), hence:

$$i_{cm} \cdot R_7 = i_{cm} \cdot R_2$$
 therefore $R_7 = R_2$

4.3.2 Peak Current

Scanning current should be I_P when positive and negative driver outputs provide respectively $i_{cm} - i_p$ and $i_{cm} + i_p$, therefore

$$i_{cm} - i) \cdot R_7 = I_p \cdot R_1 + (i_{cm} + i) \cdot R_2$$
 and since $R_7 = R_2$: $\frac{I_p}{i} = -\frac{2R_7}{R_1}$

Choose R_1 in the 1Ω range, the value of $R_2 = R_7$ follows. Remember that i is one-quarter of driver peak-peak differential signal! Also check that the voltages on the driver outputs remain inside allowed range.

• Example: for $i_{cm} = 0.4 \text{mA}$, i = 0.2 mA (corresponding to 0.8 mA of peak-peak differential current), $I_D = 1 \text{A}$

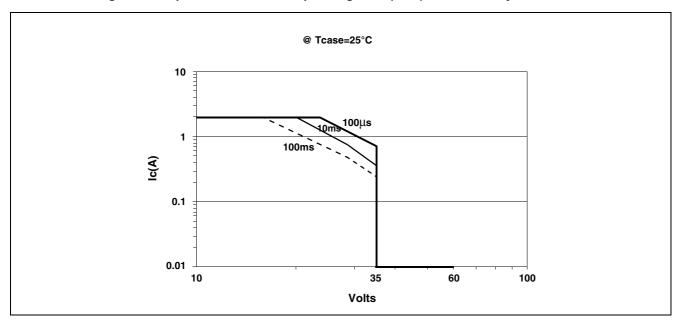
Choose $R_1 = 0.75\Omega$, it follows $R_2 = R_7 = 1.875k\Omega$

4.3.3 Ripple Rejection

Make sure to connect R₇ directly to the ground side of R₁.

4.3.4 Secondary Breakdown Diagrams

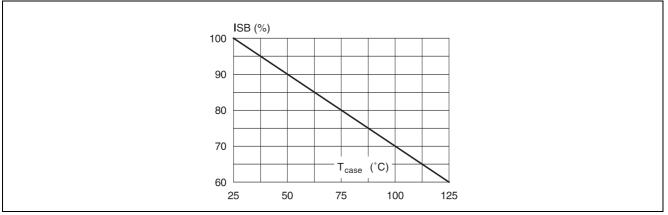
Figure 8: Output Transistor Safe Operating Area (SOA) for Secondary Breakdown



The diagram has been arbitrarily limited to max VS (35 V) and max I0 (2 A).

Application Hints STV9302B

Figure 9: Secondary Breakdown Temperature Derating Curve (ISB = Secondary Breakdown Current)



4.4 Horizontal Noise Reduction

If the level of the noise induced in the vertical deflection yoke by the horizontal deflection yoke must be reduced, a capacitor should be added in parallel with the vertical deflection yoke.

In this case the maximum recommended value of the capacitor is 100 nF.

5 Mounting Instructions

The power dissipated in the circuit is removed by adding an external heatsink. With the HEPTAWATT™ package, the heatsink is simply attached with a screw or a compression spring (clip).

A layer of silicon grease inserted between heatsink and package optimizes thermal contact. In DC-coupled applications we recommend to use a silicone tape between the device tab and the heatsink to electrically isolate the tab.

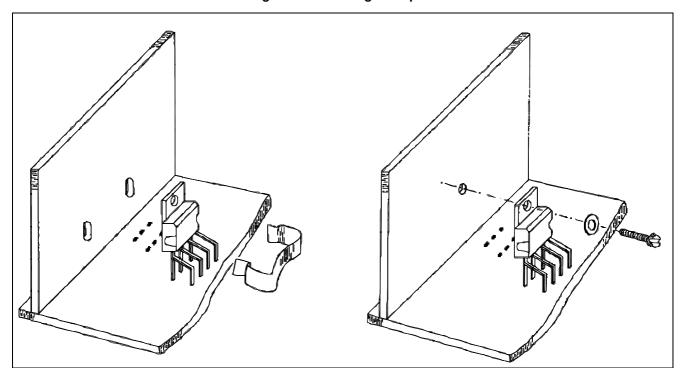


Figure 10: Mounting Examples

Pin Configuration STV9302B

6 Pin Configuration

Figure 11: Pins 1 and 7

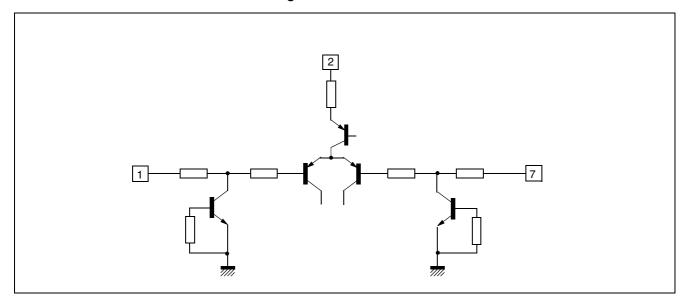
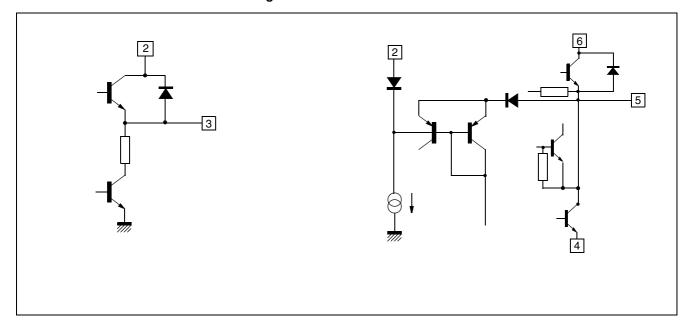


Figure 12: Pin 3 & Pins 5 and 6



7 Package Mechanical Data

L , E L1 M1 Μ C ‡ L2 H2 L3 L5 G G1 Н3 G2 F H2 L10 L4 L11 L7 L6

Figure 13: 7-pin Heptawatt Package

Table 1: Heptawatt Package

Dim.		mm				
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α			4.8			0.189
С			1.37			0.054
D	2.40		2.80	0.094		0.110
D1	1.20		1.35	0.047		0.053
E	0.35		0.55	0.014		0.022
E1	0.70		0.97	0.028		0.038
F	0.60		0.80	0.024		0.031
G	2.34	2.54	2.74	0.095	0.100	0.105
G1	4.88	5.08	5.28	0.193	0.200	0.205
G2	7.42	7.62	7.82	0.295	0.300	0.307
H2			10.40			0.409
Н3	10.05		10.40	0.396		0.409
L	16.70	16.90	17.10	0.657	0.668	0.673

Table 1: Heptawatt Package (Continued)

Dim.		mm		inches		
Dilli.	Min.	Тур.	Max.	Min.	Тур.	Max.
L1		14.92			0.587	
L2	21.24	21.54	21.84	0.386	0.848	0.860
L3	22.27	22.52	22.77	0.877	0.891	0.896
L4			1.29			0.051
L5	2.60	2.80	3.00	0.102	0.110	0.118
L6	15.10	15.50	15.80	0.594	0.610	0.622
L7	6.00	6.35	6.60	0.0236	0.250	0.260
L9		0.20			0.008	
L10	2.10		2.70	0.082		0.106
L11	4.30		4.80	0.169		0.190
М	2.55	2.80	3.05	0.100	0.110	0.120
M1	4.83	5.08	5.33	0.190	0.200	0.210
V4		40 (Typ.)				
Dia.	3.65		3.85	0.144		0.152

STV9302B Revision History

8 Revision History

Table 2: Summary of Modifications

Version	Date	Description
0.1	February 2005	First Issue

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics

© 2005 STMicroelectronics - All Rights Reserved

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

www.st.com